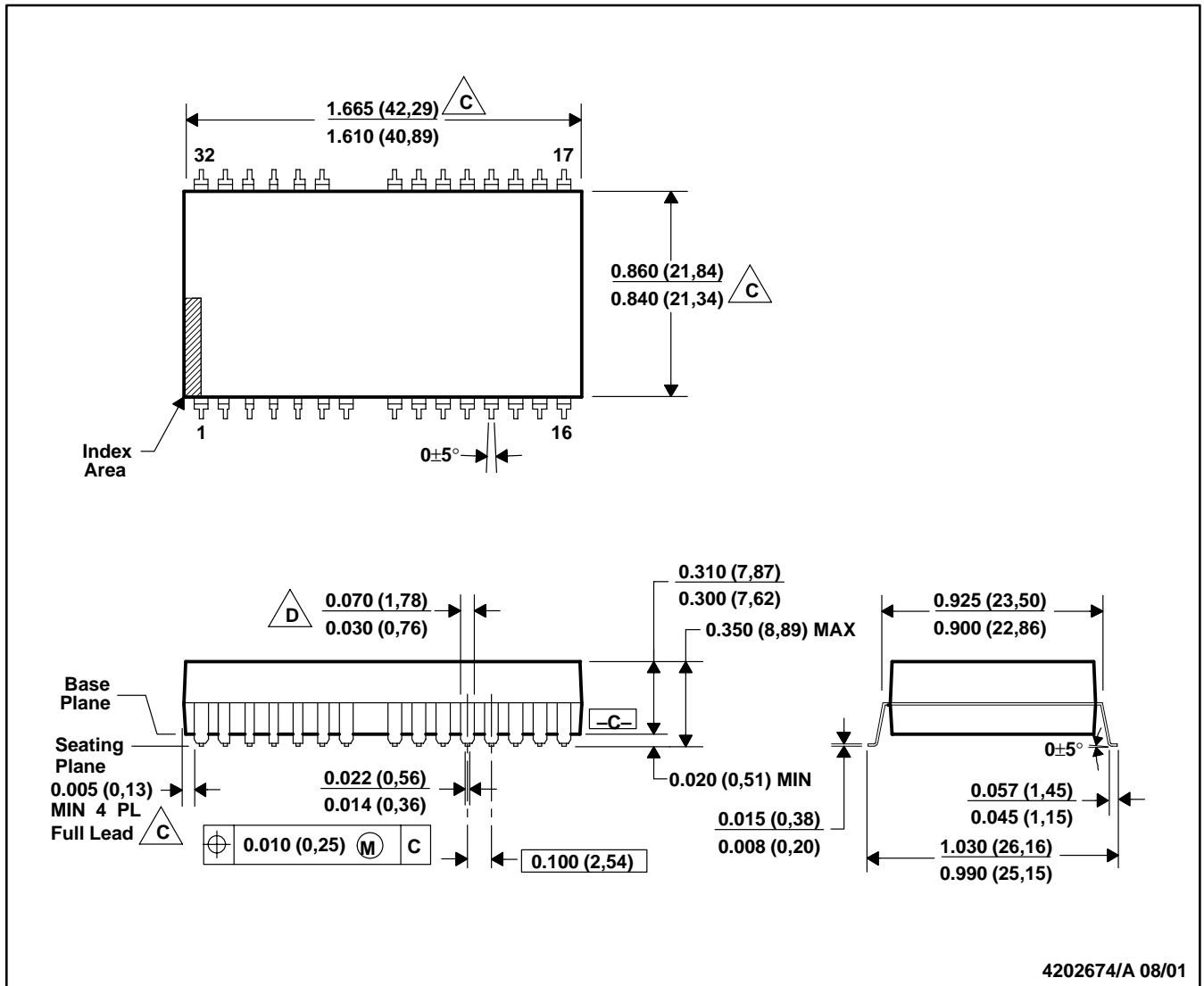


DVP (R-PDSO-G29/32)

PLASTIC SMALL-OUTLINE



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Dimensions do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010 (0,25).
 D. Maximum dimension does not include dambar protrusions. Dambar protrusions shall not exceed 0.005 (0,13).
 E. Lead shoulder dimension for leads 2, 3, 4, 5, 6, 28, 29, 30 less than nominal to maintain specified lead spacing.
 F. A visual index feature must be locate within the cross-hatched area.
 G. For automatic insertion, any raised irregularity on the top surface (step, mesa, etc.) shall be symmetrical about the lateral and longitudinal package centerlines.

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Mailing Address:

Texas Instruments
Post Office Box 655303
Dallas, Texas 75265